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(54) Title: METHOD OF METALLIZING A SILICONE RUBBER SUBSTRATE

(57) Abstract: A method of metallizing a silicone rubber substrate, the method comprising the steps of (i) depositing a primer layer of aluminum on a surface of a silicone rubber substrate, and (ii) depositing a layer of a ductile metal on the primer layer of aluminum, wherein the ductile metal is selected from gold, platinum, palladium, copper, silver, aluminum, and indium.



WO 2005/056868 A1